Dual Inverter

The NL27WZ04 is a high performance dual inverter operating from a 1.65 V to 5.5 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance.

Features

- Extremely High Speed: t_{PD} 2.0 ns (typical) at $V_{CC} = 5 V$
- Designed for 1.65 V to 5.5 V V_{CC} Operation
- Over Voltage Tolerant Inputs and Outputs
- LVTTL Compatible Interface Capability with 5 V TTL Logic with $V_{CC} = 3 V$
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current Substantially Reduces System Power Requirements
- Replacement for NC7W04
- Chip Complexity: FET = 72; Equivalent Gate = 18
- Pb–Free Packages are Available











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MARKING DIAGRAMS





M5 = Device Code

(Note: Microdot may be in either location) *Date Code orientation and/or position and underbar may vary depending upon manufacturing location.

PIN ASSIGNMENT

1	IN A1
2	GND
3	IN A2
4	OUT Y2
5	V _{CC}
6	OUT Y1

FUNCTION TABLE

A Input	Y Output
L	н
н	L

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

M = Date Code*

⁼ Pb–Free Package

MAXIMUM RATINGS

Characteristics		Symbol	Value	Unit
DC Supply Voltage		V _{CC}	-0.5 to +7.0	V
DC Input Voltage		VI	$-0.5 \le V_1 \le +7.0$	V
DC Output Voltage Out	put in HIGH or LOW State (Note 1)	Vo	$-0.5 \le V_O \le 7.0$	V
DC Input Diode Current	I _{IK}	-50	mA	
DC Output Diode Current	I _{OK}	-50	mA	
DC Output Source/Sink Current	Ι _Ο	±50	mA	
DC Supply Current Per Supply Pin		I _{CC}	±100	mA
DC Ground Current Per Ground Pin		I _{GND}	±100	mA
Storage Temperature Range		T _{STG}	-65 to +150	°C
Power Dissipation in Still Air	SC-88, TSOP-6 (Note 2)	PD	200	mW
Thermal Resistance	SC-88, TSOP-6 (Note 2)	θ_{JA}	333	°C/W
Lead temperature, 1 mm from Case for 10 Seconds	3	ΤL	260	°C
Junction Temperature Under Bias		Τ _J	+150	°C
ESD Withstand Voltage	Human Body Model (Note 3) Machine Model (Note 4) Charged Device Model (Note 5)	V _{ESD}	> 2000 > 200 N/A	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Io absolute maximum rating must be observed.
 Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
 Tested to EIA/JESD22-A114-A

4. Tested to EIA/JESD22-A115-A

5. Tested to JESD22-C101-A

RECOMMENDED OPERATING CONDITIONS

Pa	Symbol	Min	Max	Unit	
Supply Voltage	Operating Data Retention Only	V _{CC}	1.65 1.5	5.5 5.5	V
Input Voltage		VI	0	5.5	V
Output Voltage	(HIGH or LOW State)	Vo	0	5.5	V
Operating Free–Air Temperature		T _A	-40	+85	°C
Input Transition Rise or Fall Rate	V _{CC} = 2.5 V ±0.2 V V _{CC} =3.0 V ±0.3 V V _{CC} =5.0 V ±0.5 V	Δt/ΔV	0 0 0	20 10 5	ns/V

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	T _A = 25°C		-40°C ≤ .	T _A ≤ 85°C		
Parameter	Condition	Symbol	(V)	Min	Тур	Max	Min	Max	Unit
High-Level Input Voltage		V _{IH}	1.65–1.95	0.75 V _{CC}			0.75 V _{CC}		V
			2.3 to 5.5	0.7 V _{CC}			0.7 V _{CC}		
Low-Level Input Voltage		V _{IL}	1.65–1.95			0.25 V _{CC}		0.25 V _{CC}	V
			2.3 to 5.5			0.3 V _{CC}		0.3 V _{CC}	
High-Level Output	I _{OH} = -100 μA	V _{OH}	1.65 to 5.5	V _{CC} – 0.1	V _{CC}		V _{CC} – 0.1		V
Voltage V _{IN} = V _{IL}	I _{OH} = -3 mA		1.65	1.29	1.52		1.29		
	I _{OH} = -8 mA		2.3	1.9	2.1		1.9		
	I _{OH} = -12 mA	-	2.7	2.2	2.4		2.2		
	I _{OH} = -16 mA		3.0	2.4	2.7		2.4		
	I _{OH} = -24 mA		3.0	2.3	2.5		2.3		
	I _{OH} = -32 mA		4.5	3.8	4.0		3.8		
Low–Level Output	I _{OL} = 100 μA	V _{OL}	1.65 to 5.5			0.1		0.1	V
Voltage V _{IN} = V _{IH}	I _{OL} = 3 mA		1.65		0.08	0.24		0.24	
	I _{OL} = 8 mA		2.3		0.20	0.3		0.3	
	I _{OL} = 12 mA		2.7		0.22	0.4		0.4	
	I _{OL} = 16 mA		3.0		0.28	0.4		0.4	
	I _{OL} = 24 mA		3.0		0.38	0.55		0.55	
	I _{OL} = 32 mA		4.5		0.42	0.55		0.55	
Input Leakage Current	$V_{IN} = V_{CC} \text{ or } GND$	I _{IN}	0 to 5.5			±0.1		±1.0	μΑ
Power Off–Output Leakage Current	V _{OUT} = 5.5 V	I _{OFF}	0			1		10	μΑ
Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	I _{CC}	1.65 to 5.5			1		10	μΑ

AC ELECTRICAL CHARACTERISTICS t_{R} = t_{F} = 2.5 ns; C_{L} = 50 pF; R_{L} = 500 Ω

		$V_{CC} \qquad T_{A} = 25^{\circ}C \qquad -40^{\circ}C \leq T_{A} \leq 85^{\circ}C$		T _A = 25°C		Γ _A ≤ 85°C			
Parameter	Condition	Symbol	(V)	Min	Тур	Max	Min	Max	Unit
Propagation Delay	$R_L = 1 M\Omega, C_L = 15 pF$	t _{PLH}	1.65	1.8	2.3	9.2	1.8	11.0	ns
(Figure 3 and 4)	$R_L = 1 M\Omega, C_L = 15 pF$	^t PHL	1.8	1.8	4.4	7.6	1.8	8.4	
	$R_L = 1 M\Omega, C_L = 15 pF$		2.5 ± 0.2	1.2	3.0	5.1	1.2	5.6	
	$R_L = 1 M\Omega, C_L = 15 pF$		3.3 ± 0.3	0.8	2.2	3.4	0.8	3.8	
	$R_L = 500 \ \Omega, \ C_L = 50 \ pF$			1.2	2.9	4.5	1.2	5.0	
	$R_L = 1 M\Omega, C_L = 15 pF$		5.0 ± 0.5	0.5	18	2.8	0.5	3.1	
	$R_L = 500 \ \Omega, \ C_L = 50 \ pF$			0.8	2.3	3.6	0.8	4.0	

CAPACITIVE CHARACTERISTICS

Parameter	Symbol	Condition	Typical	Unit
Input Capacitance	C _{IN}	V_{CC} = 5.5 V, V_{I} = 0 V or V_{CC}	2.5	pF
Power Dissipation Capacitance (Note 6)	C _{PD}	10 MHz, V_{CC} = 3.3 V, V_I = 0 V or V_{CC} 10 MHz, V_{CC} = 5.5 V, V_I = 0 V or V_{CC}	9 11	pF

6. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.



 $\label{eq:propagation delays} \begin{array}{l} \textbf{PROPAGATION DELAYS} \\ t_R = t_F = 2.5 \text{ ns}, 10\% \text{ to } 90\%; \text{ f} = 1 \text{ MHz}; t_W = 500 \text{ ns} \end{array}$





 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 4. Test Circuit

ORDERING INFORMATION

Device	Package	Shipping [†]
NL27WZ04DFT2	SC-88/SC70-6/SOT-363	
NL27WZ04DFT2G	SC-88/SC70-6/SOT-363 (Pb-Free)	
NL27WZ04DTT1	TSOP-6	- 3000 / Tape & Reel
NL27WZ04DTT1G	TSOP-6 (Pb-Free)	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SC-88/SC70-6/SOT-363 CASE 419B-02 ISSUE W



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. 419B-01 OBSOLETE, NEW STANDARD 419B-02.

	MIL	LIMETE	RS		INCHES	6	
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.80	0.95	1.10	0.031	0.037	0.043	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
A3		0.20 REF			0.008 RE	EF	
b	0.10	0.21	0.30	0.004	0.008	0.012	
С	0.10	0.14	0.25	0.004	0.005	0.010	
D	1.80	2.00	2.20	0.070	0.078	0.086	
Е	1.15	1.25	1.35	0.045	0.049	0.053	
е	(0.65 BS	С	0.026 BSC			
L	0.10	0.20	0.30	0.004	0.008	0.012	
HE	2.00	2.10	2.20	0.078	0.082	0.086	

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSOP-6 CASE 318G-02 ISSUE S



NOTES: 1. DIMENS

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
- CONTROLLING DIMENSION: MILLIMETER.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	м	ILLIMETE	RS		INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.90	1.00	1.10	0.035	0.039	0.043
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.25	0.38	0.50	0.010	0.014	0.020
С	0.10	0.18	0.26	0.004	0.007	0.010
D	2.90	3.00	3.10	0.114	0.118	0.122
E	1.30	1.50	1.70	0.051	0.059	0.067
е	0.85	0.95	1.05	0.034	0.037	0.041
L	0.20	0.40	0.60	0.008	0.016	0.024
HE	2.50	2.75	3.00	0.099	0.108	0.118
θ	0°	-	10°	0°	_	10°

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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